

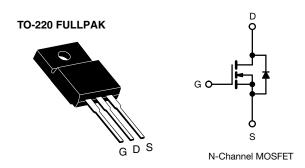
RoHS

COMPLIANT HALOGEN

FREE



EF Series Power MOSFET with Fast Body Diode



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V 0.123			
Q _g max. (nC)	120			
Q _{gs} (nC)	17			
Q _{gd} (nC)	33			
Configuration	Single			

FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High intensity discharge (HID)
 - Light emitting diodes (LEDs)
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- · Applications using the following topologies
 - LLC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free and Halogen-free	SiHF28N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (TC	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	600	V
Gate-Source Voltage			V_{GS}	± 30	7 v
Continuous Drain Current (T. 150 °C) e	V _{GS} at 10 V	T _C = 25 °C	,	28	
Continuous Drain Current (T _J = 150 °C) e	V _{GS} at 10 V	T _C = 100 °C	I _D	18	Α
Pulsed Drain Current ^a			I _{DM}	75	
Linear Derating Factor				0.31	W/°C
Single Pulse Avalanche Energy b			E _{AS}	691	mJ
Maximum Power Dissipation			P _D	39	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope T _J = 125 °C			dV/dt	70	V/ns
Reverse Diode dV/dt ^d				50	
Soldering Recommendations (Peak temperature) c	For 10 s			300	°C
Mounting Torque	M3 s	screw		0.6	Nm

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 7 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 900 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$
- e. Limited by maximum junction temperature



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.2	C/ VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	_	0.76	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Octo Course Loslines			V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
Zero Cata Valtaga Drain Current	1	V _{DS} =	= 480 V, V _{GS} = 0 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	2	mA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V I _D = 14 A		-	0.107	0.123	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 14 A	-	9.7	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	2714	-	
Output Capacitance	C _{oss}		$V_{DS} = 100 V,$	-	123	-	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}		/	-	98	-	pF
Effective output capacitance, time related ^b	$C_{o(tr)}$	V _{GS} = 0 V	/, V _{DS} = 0 V to 480 V	-	356	-	
Total Gate Charge	Q_g			_	80	120	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 14 A, V_{DS} = 480 V$	-	17	-	nC
Gate-Drain Charge	Q _{gd}			-	33	-	
Turn-On Delay Time	t _{d(on)}			-	24	48	
Rise Time	t _r	V _{DD} =	480 V, I _D = 14 A	-	40	80	
Turn-Off Delay Time	t _{d(off)}	$R_g = 9$	9.1 Ω , $V_{GS} = 10 \text{ V}$	-	82	123	ns
Fall Time	t _f			-	39	78	
Gate Input Resistance	R _g	f = 1	MHz, open drain	0.2	0.5	1.0	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	28	
Pulsed Diode Forward Current	I _{SM}			-	-	70	A
Diode Forward Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 11 \text{A}, V_{GS} = 0 \text{V}$		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			-	142	284	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 14 A, dl/dt = 100 A/us, V _B = 400 V		1.94	μC		
Reverse Recovery Current	I _{RRM}	ui/ut =	100 AV µS, VR = 400 V	-	13.2	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

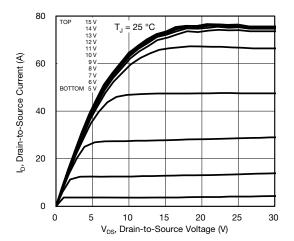


Fig. 1 - Typical Output Characteristics

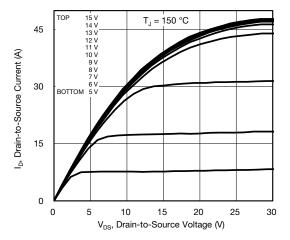


Fig. 2 - Typical Output Characteristics

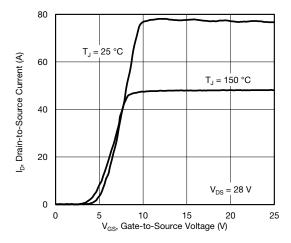


Fig. 3 - Typical Transfer Characteristics

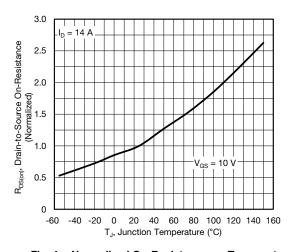


Fig. 4 - Normalized On-Resistance vs. Temperature

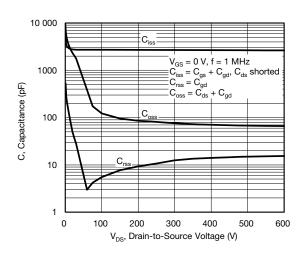


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

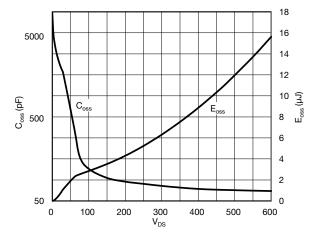


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



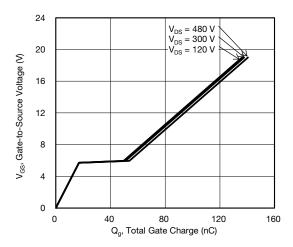


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

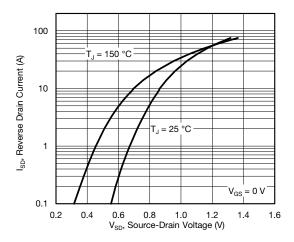


Fig. 8 - Typical Source-Drain Diode Forward Voltage

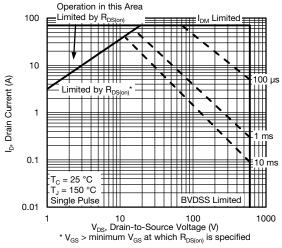


Fig. 9 - Maximum Safe Operating Area

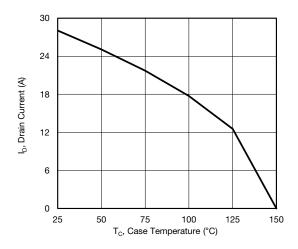


Fig. 10 - Maximum Drain Current vs. Case Temperature

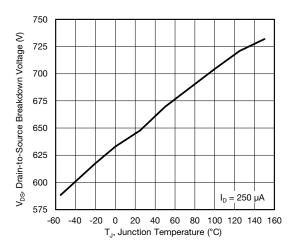


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



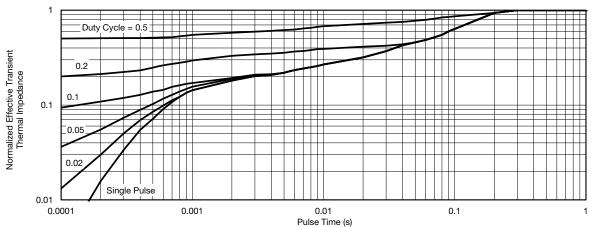


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

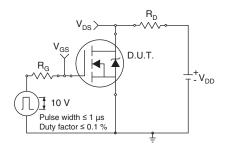


Fig. 13 - Switching Time Test Circuit

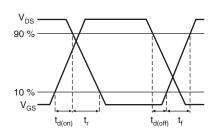


Fig. 14 - Switching Time Waveforms

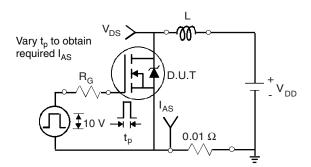


Fig. 15 - Unclamped Inductive Test Circuit

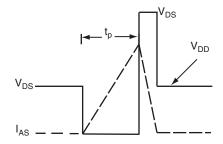


Fig. 16 - Unclamped Inductive Waveforms

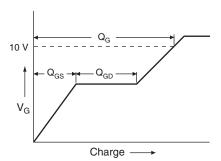


Fig. 17 - Basic Gate Charge Waveform

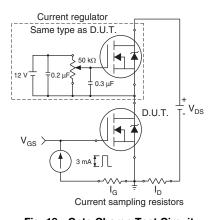
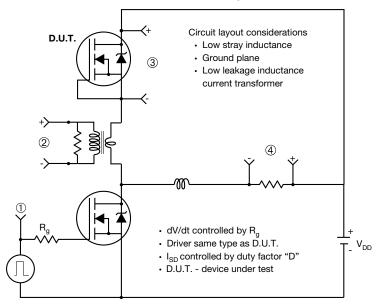


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



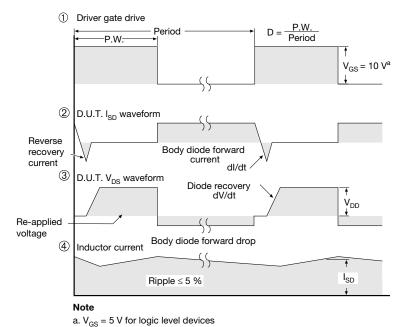


Fig. 19 - For N-Channel

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TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9



		MILLIMETERS	
DIM.	MIN.	NOM.	MAX.
Α	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
е		2.54 BSC	
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØR	3.08	3.18	3.28

Notes

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



OPTION 2: FACILITY CODE = Y



MILLIMETERS		ETERS	INCHI	CHES	
DIM.	MIN. MAX.		MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
Е	10.360	10.630	0.408	0.419	
е	2.54	2.54 BSC		0.100 BSC	
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

ECN: E19-0180-Rev. D, 08-Apr-2019

DWG: 5972

Notes

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- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
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